

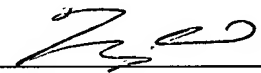
REMARKS

In this Preliminary Amendment, claim 8 has been added as a new claim. Support for this new claim can be found in the specification at, for example, pages 14 to 15, and original claims 1 and 6.

Claims 1-7 have been cancelled.

No new matter has been added. Entry and consideration of this Amendment are respectfully requested.

Respectfully submitted,



Fang Liu
Registration No. 51,283

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE



23373

PATENT TRADEMARK OFFICE

Date: July 21, 2003

APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 1-7 are canceled.

Please add the following new claims:

8. (New) A method for processing a semiconductor wafer comprising the steps of:
adhering a pressure-sensitive adhesive sheet to a semiconductor wafer, the pressure-
sensitive adhesive sheet comprising a photo-transmitting base film, and a layer comprising an
ultraviolet-curable pressure-sensitive adhesive composition comprising a photoinitiator having a
molar absorptivity at 365 nm of at least 1,000 mol⁻¹·cm⁻¹ and a maximum absorption wavelength
of at least 420 nm;

exposing the pressure-sensitive adhesive sheet to an ultraviolet ray; and
peeling the pressure-sensitive adhesive sheet from the semiconductor wafer.